



Reliability Data Report

Product Family R515

LT1999 / LT5400 / LT6000 / LT6001 /
LT6002 / LT6003 / LT6004 / LT6005 /
LT6015 / LT6016 / LT6017 / LT6020 /
LT6023 / LT6108 / LT6109 / LT6118 /
LT6119 / LT6375 / LT6558

Reliability Data Report

Report Number: R515

Report generated on: Mon Apr 18 13:27:25 PDT 2016

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES _{2, 3}
QFN/DFN	706	0630	1517	1027	0
SOIC/MSOP	1927	0552	1518	2703	0
SOT	154	0630	0630	90	0
Totals	2,787	-	-	3,820	0

HIGHLY ACCELERATED STRESS TEST AT +130 DEG C / 85% RH					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C) ⁴	No. of FAILURES
SOIC/MSOP	314	1335	1411	1205	0
SOT	154	1150	1336	591	0
Totals	468	-	-	1,796	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	1418	0720	1508	82	0
SSOP/TSSOP	74	0530	0539	10	0
SOIC/MSOP	6515	0529	1516	608	0
SOT	2314	0649	1516	125	0
Totals	10,321	-	-	825	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	995	0720	1508	237	0
SSOP/TSSOP	228	0530	0539	86	0
SOIC/MSOP	6306	0529	1516	2166	0
SOT	1671	0649	1516	372	0
Totals	9,200	-	-	2,861	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
QFN/DFN	1094	0720	1508	248	0
SSOP/TSSOP	154	0530	0539	115	0
SOIC/MSOP	5372	0529	1516	1983	0
SOT	1802	0649	1516	248	0
Totals	8,422	-	-	2,594	0

- (1) Assumes Activation Energy = 1.0 Electron Volts
 (2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =0.48 FITS
 (3) Mean Time Between Failure in Years = 237875.61
 (4) Assumes 20X Acceleration from 85 °C to +130 °C

Note 1: 1 FIT = 1 Failure in One Billion Hours.

Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning

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HIGH TEMPERATURE BAKE AT 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	225	1217	1424	225	0
SOIC/MSOP	126	1028	1440	118	0
SOT	128	0814	1513	128	0
Totals	479	-	-	471	0
HIGH TEMPERATURE BAKE AT 175 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
QFN/DFN	173	1229	1444	173	0
SOIC/MSOP	1218	1215	1444	1219	0
SOT	331	1247	1330	331	0
Totals	1,722	-	-	1,723	0